PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data	
1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	MICROCONTROLLERS/25/15305
1.3 Title of PCN	ST ROUSSET (France) additional source for STM32F411x , STM32F412x and STM32F76x/F77x listed products in M10/90nm technology.
1.4 Product Category	STM32F411x, STM32F412x, STM32F765x, STM32F767x, STM32F769x, STM32F777x and STM32F779x
1.5 Issue date	2025-05-07

2. PCN Team
2.1 Contact supplier

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication (SOP 2617)	ST Rousset (France)

4. Description of change		
	Old	New
4.1 Description	Front-end sources for Die 431 cut1.0 : - ST Crolles (France) CR300 revision A - TSMC (Taiwan) FAB14 revision 1 Front-end sources for Die 441 cut3.0 : - ST Crolles (France) CR300 revision C - TSMC (Taiwan) FAB14 revision 1 Front-end sources for Die 451 cut1.1 : - ST Crolles (France) CR300 revision Z - TSMC (Taiwan) FAB14 revision 1	Front-end sources for Die 431 cut1.0 : - ST Crolles (France) CR300 revision A - TSMC (Taiwan) FAB14 revision 1 Additional source - ST Rousset (France) RS8F revision 3 Front-end sources for Die 441 cut3.0 : - ST Crolles (France) CR300 revision C - TSMC (Taiwan) FAB14 revision 1 Additional source - ST Rousset (France) RS8F revision 2 Front-end sources for Die 451 cut1.1 : - ST Crolles (France) CR300 revision Z - TSMC (Taiwan) FAB14 revision 1 Additional source - ST Rousset (France) RS8F revision 2
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No change on Form, Fit or Function - same datasheets	

5. Reason / motivation for change	
5.1 Motivation	Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional front-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Change is visible through diffusion traceability plant, in the marking: - “9R” for TSMC Fab14 (Taiwan) - "VQ" for ST Crolles (France) - "VG" for ST Rousset (France) Please refer to PCN 15305– Additional information attached document.

7. Timing / schedule	
7.1 Date of qualification results	2025-07-30
7.2 Intended start of delivery	2025-11-04
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	15305 PCN15305_MDRF-GPAM-RER2417_M10 C300 to R8 - Die 431-441-451- Rel Plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2025-05-07

9. Attachments (additional documentations)
15305 Public product.pdf 15305 PCN15305_MDRF-GPAM-RER2417_M10 C300 to R8 - Die 431-441-451- Rel Plan.pdf 15305 _Additional information.pdf

10. Affected parts		
10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32F411CCU6TR	
	STM32F411CEU6	
	STM32F411CEU6TR	
	STM32F411RCT6	
	STM32F411RCT6TR	
	STM32F411RET6	
	STM32F411RET6TR	
	STM32F411RET7	
	STM32F411VCH6	
	STM32F411VCT6	
	STM32F411VEH6	
	STM32F411VET6	
	STM32F411VET6TR	
	STM32F412CEU6	
	STM32F412CGU6	
	STM32F412RET6	
	STM32F412RET6TR	
	STM32F412RET7	
	STM32F412RGT6	
	STM32F412RGT6TR	
	STM32F412VEH3TR	
	STM32F412VEH6	
	STM32F412VEH6TR	
	STM32F412VET3	
	STM32F412VET6	
	STM32F412VET6TR	
	STM32F412VGH6	
	STM32F412VGT6	
	STM32F412VGT6TR	
	STM32F412VGT7	
	STM32F412ZEJ3	

	STM32F412ZEJ6	
	STM32F412ZET6	
	STM32F412ZET7	
	STM32F412ZGJ6	
	STM32F412ZGT6	
	STM32F412ZGT6TR	
	STM32F765IGK6	
	STM32F765IGT6	
	STM32F765IIK6	
	STM32F765IIK7	
	STM32F765IIT6	
	STM32F765IIT7	
	STM32F765NGH6	
	STM32F765NGH7	
	STM32F765NIH6	
	STM32F765NIH6TR	
	STM32F765NIH7	
	STM32F765VGH6	
	STM32F765VGT6	
	STM32F765VGT6TR	
	STM32F765VGT7	
	STM32F765VIH6	
	STM32F765VIT6	
	STM32F765ZGT6	
	STM32F765ZGT6TR	
	STM32F765ZGT7	
	STM32F765ZIT6	
	STM32F765ZIT7	
	STM32F765ZIT7TR	
	STM32F767IGK6	
	STM32F767IGT6	
	STM32F767IIK6	
	STM32F767IIT6	
	STM32F767NGH6	
	STM32F767NIH6	
	STM32F767NIH6TR	
	STM32F767VGH6	
	STM32F767VGT6	
	STM32F767VGT7	
	STM32F767VIH6	
	STM32F767VIT6	
	STM32F767ZGT6	
	STM32F767ZIT6	
	STM32F769IGT6	
	STM32F769IIT6	
	STM32F769NGH6	
	STM32F769NIH6	
	STM32F769NIH6TR	
	STM32F777IIK6	
	STM32F777IIT6	
	STM32F777IIT7	

	STM32F777NIH6	
	STM32F777NIH6TR	
	STM32F777NIH7	
	STM32F777NIH7TR	
	STM32F777VIH6	
	STM32F777VIT6	
	STM32F777ZIT6	
	STM32F779IIT6	
	STM32F779NIH6	
	STM32F779NIH6TR	
	STM32F411RCT6GEM	
	STM32F777IIK7	
	STM32F767VIT7	

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